

0.6um BICMOS Vanguard Qualification Summary

TABLE 1A: LTC4270 QUALIFICATION RESULTS

TEST	SPECIFICATION	SAMPLE SIZE (LOTS X SAMPLE)	RESULTS
High Temperature Operating Life (HTOL)	JEDEC JESD22-A108	3 x 77	Pass
Highly Accelerated Stress Test (HAST)**	JEDEC JESD22-A110	3 x 77	Pass
Temperature Cycle (TC)**	JEDEC JESD22-A104	3 x 77	Pass
Autoclave (AC)**	JEDEC JESD22-A102	3 x 77	Pass
High Temperature Storage Life (HTSL)	JEDEC JESD22-A103	3 x 45	Pass
Early Life Failure Rate (ELFR)	MIL-STD-883, M1015	3 x 800	Pass

TABLE 1B: LTC3850 QUALIFICATION RESULTS

TEST	SPECIFICATION	SAMPLE SIZE (LOTS X SAMPLE)	RESULTS
High Temperature Operating Life (HTOL)	JEDEC JESD22-A108	3 x 77	Pass
Highly Accelerated Stress Test (HAST)**	JEDEC JESD22-A110	3 x 77	Pass
Temperature Cycle (TC)**	JEDEC JESD22-A104	3 x 77	Pass
Autoclave (AC)**	JEDEC JESD22-A102	3 x 77	Pass
High Temperature Storage Life (HTSL)	JEDEC JESD22-A103	3 x 45	Pass
Early Life Failure Rate (ELFR)	MIL-STD-883, M1015	3 x 800	Pass

TABLE 1C: LTC3112 QUALIFICATION RESULTS

TEST	SPECIFICATION	SAMPLE SIZE (LOTS X SAMPLE)	RESULTS
High Temperature Operating Life (HTOL)	JEDEC JESD22-A108	3 x 77	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC JESD22-A110	3 x 77	Pass
Temperature Cycle (TC)*	JEDEC JESD22-A104	3 x 77	Pass
Autoclave (AC)*	JEDEC JESD22-A102	3 x 77	Pass
High Temperature Storage Life (HTSL)	JEDEC JESD22-A103	3 x 45	Pass
Early Life Failure Rate (ELFR)	MIL-STD-883, M1015	3 x 800	Pass



Vanguard International Semiconductor Corporation

Vanguard International Semiconductor Summary

- Plant Address

123, Park Ave-3rd, Science-Based Industrial Park, Hsinchu, Taiwan 30077, R.O.C.

- Headcount

5,200

- Total Building size in sq. ft. and fab size in sq. meters

880,543.3 sq. feet (Building 1)

- Clean room floor space in sq. meters

12,600 sq. meters (Building 1)

- Fab utilization in percent

Fab 1: 100%

- Land Area in sq. meters

41,925 sq. meters

- Wafer capacity for each facility

Fab 1: 87K wafers per month (ADI's material is scheduled to run in Fab 1)

- A list of certifications (i.e. TS16949, ISO-14001, etc.)

- ISO 9001 Quality Management System (since 1996)
- ISO 14001 Environment Management System (since 1997)
- OHSAS 18001 Health & Safety Management System (since 2003)
- QC 080000 Hazardous Substance Management System (since 2007)
- ISO 27001 Information Security Management System (since 2015)
- IATF 16949 Automotive Quality Management System (since 2018)

Confidential Statement

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DeltaQualifikationsMatrix

Allgemeines

Kurze Produkt- und Technologiezyklen elektronischer Bauelemente sowie neue Umweltauflagen führen häufig zu prozess- und werkstofftechnischen Änderungen an Bauelementen, Leiterplatten, Verbindungstechnik und Schaltung, welche evaluiert werden müssen. Eine geeignete Methodik zur Handhabung von Änderungen an elektronischen Bauelementen beschreibt die ZVEI "Guideline for Customer Notifications of Product and/or Process Changes (PCN) of Electronic Components specified for Automotive Applications". Ein wesentlicher Teil dieser Guideline sind die hier vorliegenden Matrizen, welche sich als Empfehlungen für die Evaluierung von typischen Änderungen an elektronischen Bauelementen verstehen. Dies sollte Teil des offenen und risikobewussten Dialoges zwischen Lieferant und Kunden sein.

Diese DeltaQualifikationsMatrizen wurden durch den Industriearbeitskreis "PCN DeltaQualifikationsMatrix" und den Bautelexperten des ZVEI Arbeitskreis "PCN-Methodik" erarbeitet. Der Inhalt wurde basierend auf dem aktuellen Stand der Technik erstellt und erhebt keinen Anspruch auf Vollständigkeit. Im Einzelfall ist ggf. ein abweichendes Vorgehen abzustimmen, da kundenspezifische Vereinbarungen zur Qualifikation zu berücksichtigen sind.

Anwendung der DeltaQualifikationsMatrix (auszufüllen durch den Bauelementhersteller)

- a) Diese Tabelle ist nur bei Änderungen anzuwenden. Neuqualifikationen und Sonderqualifikation (z.B. Verguß von Modulen) sowie Information Notes bleiben von diesen Matrizen unberührt.
- b) Ist eine Änderung in dieser Tabelle nicht aufgeführt, so ist der Qualifikationsumfang zwischen Kunde und Lieferant abzustimmen.
- c) Die Matrix der Aktiven Bauelemente ist so aufgebaut, dass zwischen integrierten Halbleitern (AEC-Q100 Rev. H) und diskreten Halbleitern (AEC-Q101 Rev. D1) auszuwählen ist (Zelle D4). Für passive Bauelemente gilt die AEC-Q200. Für LED's gilt die AEC-Q102. Für Multi-Chip-Module gilt die AEC-Q104.
- d) Alle Änderungen in der PCN sind in der Spalte B durch einen Kreuz (x) zu markieren und werden dadurch farblich hervorgehoben. Sofern dies geschehen ist, werden im Feld "Tests, which should be considered for the appropriate process change" alle in Betracht zu ziehenden Zuverlässigkeitstests angezeigt.
- e) In "Tests, which should be considered for the appropriate process change after selection of condition table" wird die Anpassung der in Betracht zu ziehenden Tests in Folge der Relevanz bezüglich der Änderung berücksichtigt.
- Dazu ist die Tabelle "Conditions" entsprechend der Auswahl (A/B/C) mit einem (x) zu bewerten.
- f) In "Suppliers performed tests" dokumentiert der Bauelementhersteller die durchgeführten bzw. geplanten Tests.
- g) Falls von der Testempfehlung abgewichen wird, so sollten diese Abweichungen vom Bauelementhersteller angezeigt und kommentiert werden. Hierzu ist der Bereich "Reason for exception of tests" zu verwenden. Werden die in Betracht zu ziehenden Tests durch generische Daten (G) belegt, ist dies ebenfalls hier anzugeben und zu begründen.

Die Einstufung des Untersuchungslevel erfolgt in folgende Kategorien

- "C: Component level": Die Evaluierung der Änderung am Bauelement ist durch Untersuchungen ausschließlich am Bauelement beim Bauelementhersteller durchführbar. Zur Evaluierung der Änderung dürfen Ergebnisse aus bereits durchgeföhrten Untersuchungen herangezogen werden, wenn diese zu einem ähnlichen Bauelement bereits vorliegen (**Generische Daten**).
 - "B: Board level": Die beschriebene Änderung hat möglicherweise Einfluss auf die Verarbeitbarkeit des Bauelements im Steuergerät. Die Evaluierung der Änderung wird wie unter C beim Bauelementhersteller durchgeführt. Zusätzlich ist durch den Kunden/Steuergerätehersteller die Verarbeitbarkeit zu prüfen, die z.B. abhängig von der Änderung, Zuverlässigkeitstests auf applikationsrelevanten Testboards erforderlich.
 - "A: Application level": Die beschriebene Änderung hat möglicherweise Einfluss auf die Applikation/ das Steuergerät. Die Evaluierung der Änderung wird wie unter C oder B durchgeführt. Zusätzlich ist vom Kunden/Steuergerätehersteller der Einfluss der Änderung im Steuergerät durch geeignete Untersuchungen zu bewerten. Dieses Vorgehen ist mit dem OEM abzustimmen. Hierbei ist zu berücksichtigen, ob die Steuergeräte-/ Baugruppenanforderungen durch andere Qualifikationen bereits hinreichend abgesichert sind (**applikationsspezifische Risikobetrachtung**).
- " *: Not relevant for qualification matrix": Änderungen(en), die nicht in A, B oder C eingestuft werden können und somit nicht relevant für die DeQuMa sind

Information Notes

Änderungen die nur eine Information Note benötigen (bei der Bewertung Risk on Supply Chain als "I" gekennzeichnet), dürfen nicht in der DeQuMa angekreuzt werden, da Sie ansonsten den erforderlichen Evaluierungslevel verfälschen. Für als "I" bewertete Änderungen ist das Information Note Formblatt zu verwenden.

Wichtige Hinweise

- Zur formgerechten Anwendung der DeltaQualifikationsMatrizen steht auf der Homepage des ZVEI AK ein Tutorial bereit (ZVEI-Tutorial).
- ID Nummer: ist eine eindeutige Identifikationsnummer für jede angegebene Änderung, die in den ZVEI PCN DeltaQualifikationsMatrizen identifiziert ist. Die gleiche ID Nummer wird zur Identifizierung der Änderung im PCN Form Sheet verwendet.
- Die mittels Matrix identifizierten Tests sind in **Betracht zu ziehen**, d.h. es ist zu prüfen, ob der jeweilige Test für die spezifische Änderung in dieser Form notwendig ist. Abweichungen oder generische Daten sind im Detail zu begründen.
- Die Spalte "Further applicable conditions", Bemerkungen und Fußnoten sind unbedingt zu beachten, da sie wichtige Hinweise und Einschränkungen enthalten.
- Zur Nutzung aller Funktionen muss in Excel die Anwendung von Makros freigegeben sein.

DeltaQualificationMatrix

General

Short product and technology cycles as well as new environmental regulations frequently result in process and material changes of components, printed circuit boards, assembly techniques and circuit layout which have to be evaluated. The ZVEI "Guideline for Customer Notifications of Product and/or Process Changes (PCN) of Electronic Components specified for Automotive Applications" describes an appropriate methodology for dealing with changed electronic components. The qualification matrices in this guideline are recommendations for how to assess typical changes of electronic components. These recommendations promote an open risk-based discussion between supplier and customer regarding qualifications.

The DeltaQualificationMatrices were developed by the Industry Task Force Team "PCN-DeltaQualificationMatrix" together with component experts from the ZVEI Working Group "PCN-Methodology". Actual content represents state-of-the-art technology and does not claim to be comprehensive. Deviation from proposed guideline should be mutually agreed as customer specific requirements have to be considered.

DeltaQualificationMatrix Application (completion by component manufacturer)

- a) This table has to be used for changes only. The matrices are not applicable for new product, special qualifications (for instance for encapsulation of module) or Information Notes.
- b) If a change is not listed in this table, the qualification plan has to be defined and agreed between customer and supplier.
- c) The matrix for Active Components requires the user to choose between integrated circuits (AEC-Q100 Rev. H) and discrete semiconductors (AEC-Q101 Rev. D1) (cell D4). For Passive Components AEC-Q200 is used. For LED's the AEC-Q102 is used. For Multi-Chip-Modules the AEC-Q104 is used.
- d) All changes as listed in the PCN have to be marked by a cross (x) in column B and will appear colored. The relevant reliability tests are then shown in "Tests, which should be considered for the appropriate process change".
- e) In "Tests, which should be considered for the appropriate process change after selection of condition table" is for modification of the found relevant tests under consideration of the weight of change. Related table "Conditions" has to be assessed per proposed letters with an (x).
- f) In "Suppliers performed tests" the component manufacturer documents the planned and performed tests.
- g) In case of deviations from tests, which should be considered this should be notified and commented by the component manufacturer in the area "Reason for exception of tests". Test results in form of generic data (G) are allowed when notified and justified.

Evaluation Levels are categorized as follows

"C: Component level": The evaluation of a change at component level by the component manufacturer is sufficient. Generic data from other relevant evaluations can be used.

"B: Board level": The intended change described in the PCN may influence processability / manufacturability of the component at board level. Therefore additional evaluation by customer may be necessary, for example reliability tests on application relevant testboards, depending on change.

"A: Application level": The intended change described in the PCN may influence the properties of the application (e.g. Electronic Control Unit). In addition to the evaluation under C or B the influence of the change in the application is evaluated by suitable investigations by the customer. The scope of the evaluation has to be aligned with the OEM. It has to be considered whether the application / assembly requirements are already sufficiently safeguarded by other qualifications (**application specific risk assessment**).

" *: Not relevant for qualification matrix": Changes which fulfill neither A nor C definitions

Information Notes

Changes indicated as "I" shall not be marked in the DeQuMa. For those changes the Information Note sheet shall be used. As the DeQuMa is desired for PCN only, a marking of "I"-changes would automatically influence evaluation level and test effort.

Important Notes

- To use the matrices in the right form the ZVEI working group provides a Tutorial on its homepage (ZVEI-Tutorial)
- ID number: is a unique identification number for each indicated change defined in the ZVEI PCN DeltaQualificationMatrices. The same ID number is used in the PCN Form sheet to identify the change.
- Tests identified by the matrix have to be considered and checked if they are necessary to assess the specific change. Test modifications or generic data have to be justified in detail.
- "Further applicable conditions", comments and notes need attention, as they provide important hints and limitations.
- In order to use all functions in EXCEL, macros have to be allowed.

History of DeQuMa

Version	Remarks
2.0	Revised by ZVEI PCN Methodology Workgroup in March 2015
2.1	Released March 2015
2.1.1	Active Components - delete write protection in comments
2.2	Solved problems with some ActiveX configurations
2.2.2	Solved Problems in Active Components
2.2.3	Solved Problems ActiveX, Active Components SEM-DE-02 (Design changes in routing) error fixed
2.2.4	Minor fixes
3.0	General Revision by ZVEI PCN Methodology Workgroup in June 2016 Changes are indicated by underlining in the read only version named Changes_DeQuMa_rev3_vs_rev2.xlsx
3.0.4	Expert Release
3.0.5	Fixing of macro bugs
3.1	Final Release (orthographic and punctuation corrections)
4.0	General Revision by ZVEI PCN Methodology Workgroup in July 2019. Multi Chip Modules newly added to DeQuMa LED Components now based on the AEC Q102 Further Changes see separate PDF's Excel-File , where changes are indicated by underlining
4.1	LED worksheet: Content of columns had been swapped due to rearrangement and omission of columns.

Worked on: (Name, Function)	Cari Iwashita
Date:	26/06/2020
PCN number:	PCN_20_0245
Signature:	[Signature]
For integrated circuit or discrete semiconductor products before release	AEC-Q100 Revision H -

Form provided by EWEI - Revision 4.1 - November 2011

PACKAGING/HOPPING		
SEM-PS-01	Packing/hopping specification change.	P
SEM-PS-02	Change of carrier (new reel)	P
SEM-PS-03	Change of carrier (new reel)	
SEM-PS-04	Change of labelling	
EQUIPMENT		
SEM-EQ-01	Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product	
SEM-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment/tool) without change of process.	
SEM-EQ-03	Change in final test equipment type leading to a different test concept	
TEST FLOW		
SEM-TF-01	Move of all or part of electrical wafer test and/or final test to a different test site.	P
SEM-TF-02	Test fixture header or redefinition Check impact on SEMA-HN-01 Check impact on SEMA-HN-02 Check impact on SEMA-HN-03	
G-GATE		
SEM-GG-01	Change of the test coverage/test flow used by the supplier to ensure data sheet compliance (e.g. administration/definition of electrical measurement/test flow block; identification/assignment of non-recurring procedure or wafering).	P
Tests, which should be considered for the appropriate process change.		
Tests, which should be considered for the appropriate process change after selection of condition table.		
Suppliers performed tests (mark with an "X" for done or "0" for generic)		
Reason for exception of tests and/or usage of generic data:		
None of the products use copper wire.		

— Not required.																																			
I Information field required.																																			
P PCN required.																																			
<p style="margin-left: 30px;">A letter or “*” indicates that performance of that stress test should be considered for the appropriate process change. A “0” indicates that no stress test is required. A “*” is recommended additionally by ZVEI</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td>CONDITIONS</td><td style="text-align: right;">No</td></tr> <tr><td>B For components with periphery</td><td style="text-align: right;">X</td></tr> <tr><td>B For components with low cure time</td><td style="text-align: right;">X</td></tr> <tr><td>C If bond to leadframe</td><td style="text-align: right;">X</td></tr> <tr><td>D Dielectric bridge</td><td style="text-align: right;">X</td></tr> <tr><td>E Thickness only</td><td style="text-align: right;">X</td></tr> <tr><td>F MEMS element only</td><td style="text-align: right;">X</td></tr> <tr><td>H Height only</td><td style="text-align: right;">X</td></tr> <tr><td>J EPROM or EEPROM</td><td style="text-align: right;">X</td></tr> <tr><td>L Lead frame</td><td style="text-align: right;">X</td></tr> <tr><td>M For devices requiring PTC</td><td style="text-align: right;">X</td></tr> <tr><td>N Passivation and gate oxides</td><td style="text-align: right;">X</td></tr> <tr><td>P Protection layer or coating dielectric</td><td style="text-align: right;">X</td></tr> <tr><td>O Wire diameter decrease</td><td style="text-align: right;">X</td></tr> <tr><td>T Only for Solder Ball SW</td><td style="text-align: right;">X</td></tr> <tr><td>X Only for die with wire-bonded-in parts</td><td style="text-align: right;">X</td></tr> <tr><td>Z For “burn in” changes IOL or ELFR recommended</td><td style="text-align: right;">X</td></tr> </table> <p style="margin-left: 30px;">=> Please mark “NO” with “X”, default is “YES”!</p>		CONDITIONS	No	B For components with periphery	X	B For components with low cure time	X	C If bond to leadframe	X	D Dielectric bridge	X	E Thickness only	X	F MEMS element only	X	H Height only	X	J EPROM or EEPROM	X	L Lead frame	X	M For devices requiring PTC	X	N Passivation and gate oxides	X	P Protection layer or coating dielectric	X	O Wire diameter decrease	X	T Only for Solder Ball SW	X	X Only for die with wire-bonded-in parts	X	Z For “burn in” changes IOL or ELFR recommended	X
CONDITIONS	No																																		
B For components with periphery	X																																		
B For components with low cure time	X																																		
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P Protection layer or coating dielectric	X																																		
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T Only for Solder Ball SW	X																																		
X Only for die with wire-bonded-in parts	X																																		
Z For “burn in” changes IOL or ELFR recommended	X																																		

MATERIAL	
CERAMIC / TANTILLUM	PAS-CER-MM-01 Change of material composition - Ceramic Binder
CERAMIC / TANTILLUM	PAS-CER-MM-02 Change of material composition - Tantalum Binder
CERAMIC / TANTILLUM	PAS-CER-MM-03 Change of material composition - Dielectric
CERAMIC / TANTILLUM	PAS-CER-MM-04 Change of material composition - Electrode Alum
CERAMIC / TANTILLUM	PAS-CER-MM-05 Change of material composition - Electrode Material
CERAMIC / TANTILLUM	PAS-CER-MM-06 Change of material composition - Electrode Paste
CERAMIC / TANTILLUM	PAS-CER-MM-07 Change of material composition - Electrode Thicknes
CERAMIC / TANTILLUM	PAS-CER-MM-08 Change of material composition - Lead material
CERAMIC / TANTILLUM	PAS-CER-MM-09 Change of material composition - Lead material - Terminator
CERAMIC / TANTILLUM	PAS-CER-MM-10 Change of material composition - Lead material - Terminator
CERAMIC / TANTILLUM	PAS-CER-MM-11 Change of supplier or material
DESIGN	
CERAMIC / TANTILLUM	PAS-CER-DE-01 Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead
CERAMIC / TANTILLUM	PAS-CER-DE-02 Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead
CERAMIC / TANTILLUM	PAS-CER-DE-03 Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead
CERAMIC / TANTILLUM	PAS-CER-DE-04 Changes of inner connection - Electrode Thickness
CERAMIC / TANTILLUM	PAS-CER-DE-05 Changes of inner construction - Layer Thickness
CERAMIC / TANTILLUM	PAS-CER-DE-06 Changes of inner construction - Layer Thickness
CERAMIC / TANTILLUM	PAS-CER-DE-07 Changes of inner construction - Number of layers
CERAMIC / TANTILLUM	PAS-CER-DE-08 Changes of inner construction - Number of layers (Alumina) - always in combination with PAS-CER-DE-05
PROCESS	
CERAMIC / TANTILLUM	PAS-CER-PR-01 Change in process technology or manufacturing methods - Clean
CERAMIC / TANTILLUM	PAS-CER-PR-02 Change in process technology or manufacturing methods - Electrode apply
CERAMIC / TANTILLUM	PAS-CER-PR-03 Change in process technology or manufacturing methods - Firing
CERAMIC / TANTILLUM	PAS-CER-PR-04 Change in process technology or manufacturing methods - Leaching
CERAMIC / TANTILLUM	PAS-CER-PR-05 Change in process technology or manufacturing methods - Particle Size
CERAMIC / TANTILLUM	PAS-CER-PR-06 Change in process technology or manufacturing methods - ScreenPrinting
CERAMIC / TANTILLUM	PAS-CER-PR-07 Change in process technology or manufacturing methods - Screening
CERAMIC / TANTILLUM	PAS-CER-PR-08 Change in process technology or manufacturing methods - Termination
CERAMIC / TANTILLUM	PAS-CER-PR-09 Change in process technology or manufacturing methods - Wet coating
CERAMIC / TANTILLUM	PAS-CER-PR-10 Change in process technology or manufacturing methods - X-ray
PACKAGING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS	
CERAMIC / TANTILLUM	PAS-CER-PN01 Packing / shipping specification change (bowing of tinnedleads)
CERAMIC / TANTILLUM	PAS-CER-PN02 Dry pack requirements change
CERAMIC / TANTILLUM	PAS-CER-PN03 Change of carrier (tray, reel)
PACKAGING / SHIPPING - VISUAL INSPECTION	
CERAMIC / TANTILLUM	PAS-CER-PI-01 Change of labelling
CERAMIC / TANTILLUM	PAS-CER-PI-02 Change of product marking
CERAMIC / TANTILLUM	PAS-CER-PI-03 Change of packing/shipping specification
LOGISTICS/CAPACITY TESTING - EQUIPMENT	
CERAMIC / TANTILLUM	PAS-CER-EQ-01 Production from a new equipment which uses a different technology or which due to its unique features cannot be compared to reference the energy of the final product
CERAMIC / TANTILLUM	PAS-CER-EQ-02 Production from a new equipment which uses the same basic technology (replacement / extension or extension of existing equipment pool)
CERAMIC / TANTILLUM	PAS-CER-EQ-03 Change in final test equipment that uses a different technology
LOGISTICS/CAPACITY TESTING - PROCESS FLOW	
CERAMIC / TANTILLUM	PAS-CER-PF-01 Manufacturing site transfer or movement of a part of production process to a different location/site
CERAMIC / TANTILLUM	PAS-CER-PF-02 Elimination or addition of a manufacturing step
LOGISTICS/CAPACITY TESTING - Q-GATE	
CERAMIC / TANTILLUM	PAS-CER-QG-01 Change in test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/reduction of electrical measurement/test flow, reduction/increasement of number of samples)
FILM CAPACITORS	
ANY	
Film capacitors	PAS-FLM-AN-01 Any change in impact agreed upon technical contractual agreements
Film capacitors	PAS-FLM-AN-02 Any change in impact on processability/manufacturability at customer, which is not covered in technical contractual agreements
DATASHEET	
Film capacitors	PAS-FLM-DS-01 Change of datasheet parameters/electrical specification (min./max./typ. values) and / or AC/DC specification
Film capacitors	PAS-FLM-DS-02 Correction of data sheet or issue of errors
Film capacitors	PAS-FLM-DS-03 Specification of additional parameters
MATERIAL	
Film capacitors	PAS-FLM-MR-01 Change of material composition - Sealing Compound
Film capacitors	PAS-FLM-MR-02 Change of material composition - Package
Film capacitors	PAS-FLM-MR-03 Change of material composition - Lead/Terminator
Film capacitors	PAS-FLM-MR-04 Change of material composition - Metal Spray (Schoop)
Film capacitors	PAS-FLM-MR-05 Change of material composition - Film
Film capacitors	PAS-FLM-MR-06 Change of material composition - Metal foil
Film capacitors	PAS-FLM-MR-07 Change of supplier or material
DESIGN	
Film capacitors	PAS-FLM-DE-01 Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead
Film capacitors	PAS-FLM-DE-02 Changes of termination, surface finish, shape, color, appearance or dimension structure - Terminator
Film capacitors	PAS-FLM-DE-03 Changes of inner connection
Film capacitors	PAS-FLM-DE-04 Changes of termination, surface finish, shape, color, appearance or dimension structure - Appearance
Film capacitors	PAS-FLM-DE-05 Changes of inner construction - Pinfall
PROCESS	
Film capacitors	PAS-FLM-PR-01 Change of lead diameter
Film capacitors	PAS-FLM-PR-02 Change of termination area
Film capacitors	PAS-FLM-PR-03 Change of appearance
Film capacitors	PAS-FLM-PR-04 Check if MATERIAL is affected
Film capacitors	PAS-FLM-PR-05 Change of inner lead design

